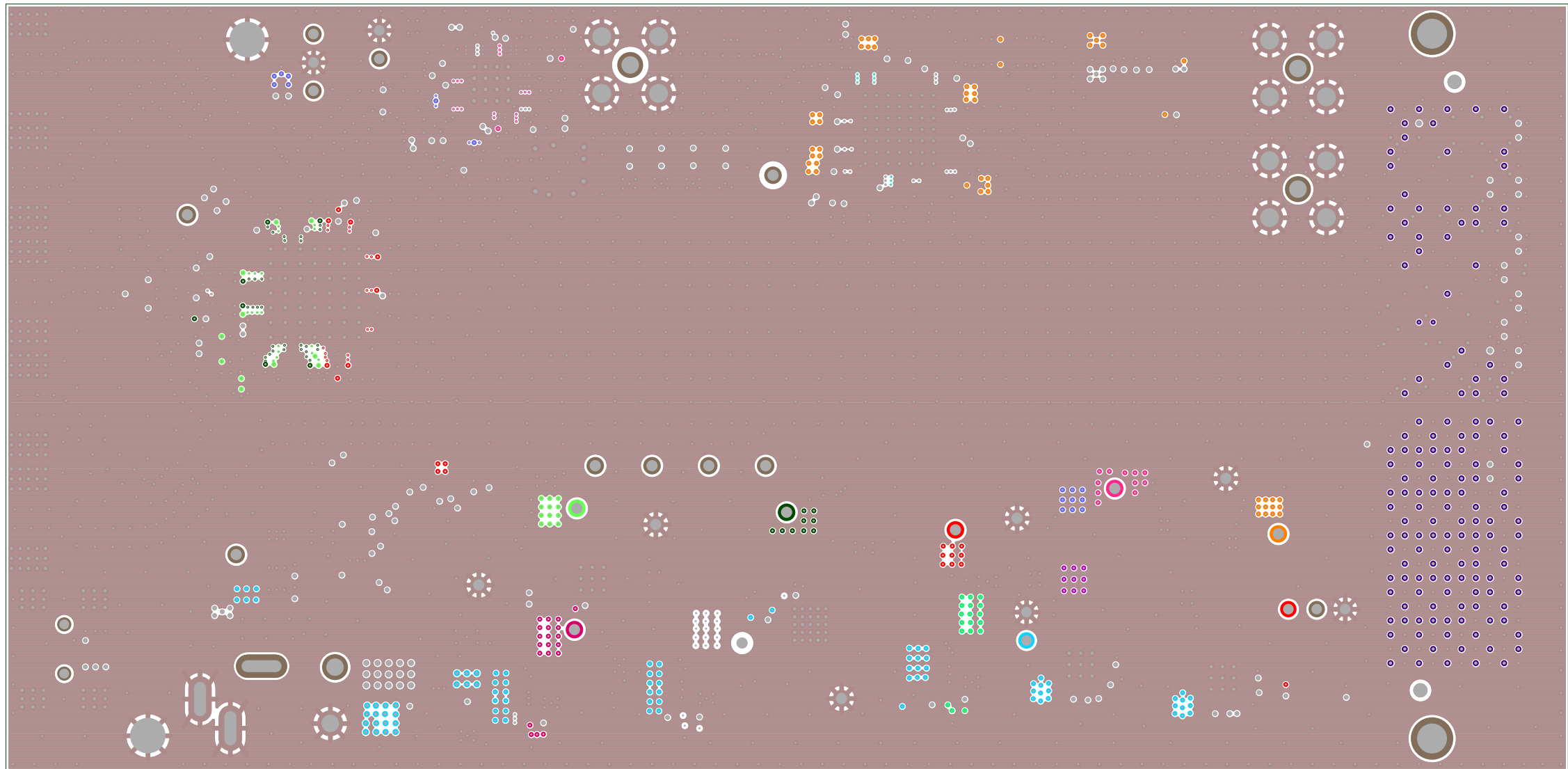
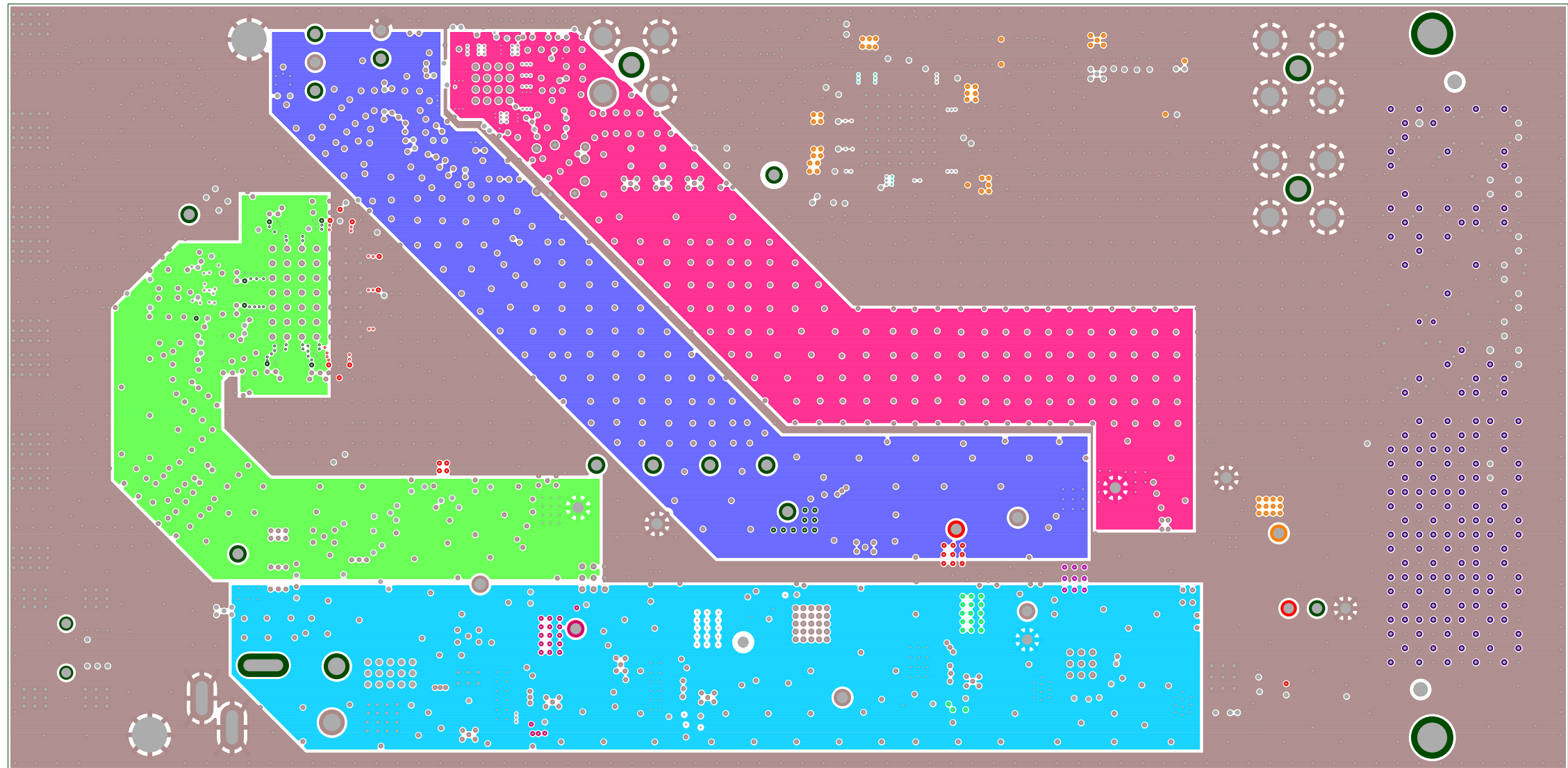


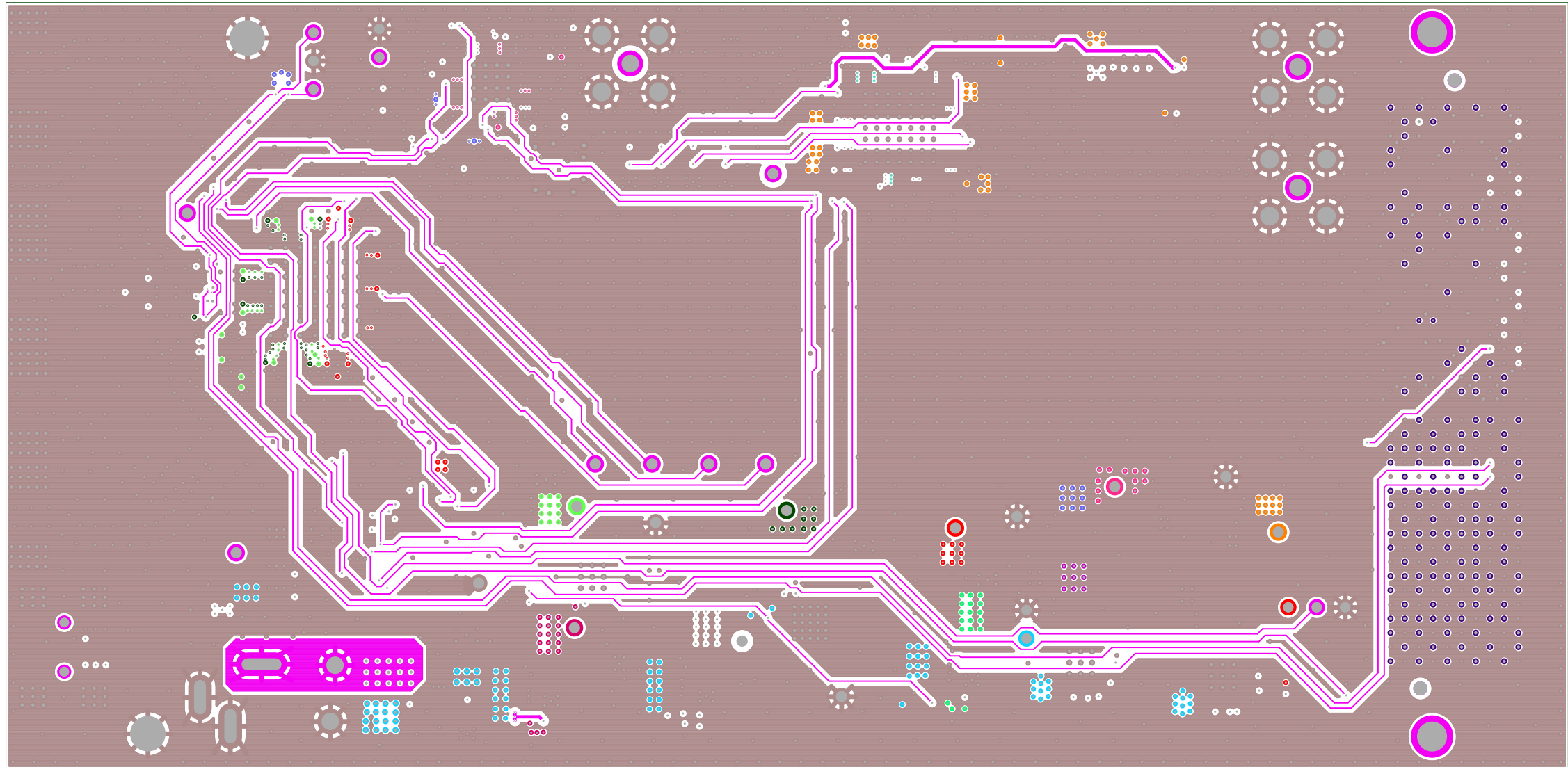
TEXAS INSTRUMENTS, INC.
 ADC3XRFXXEVM
 PCB REV E
 SILEKSCREENSTOP



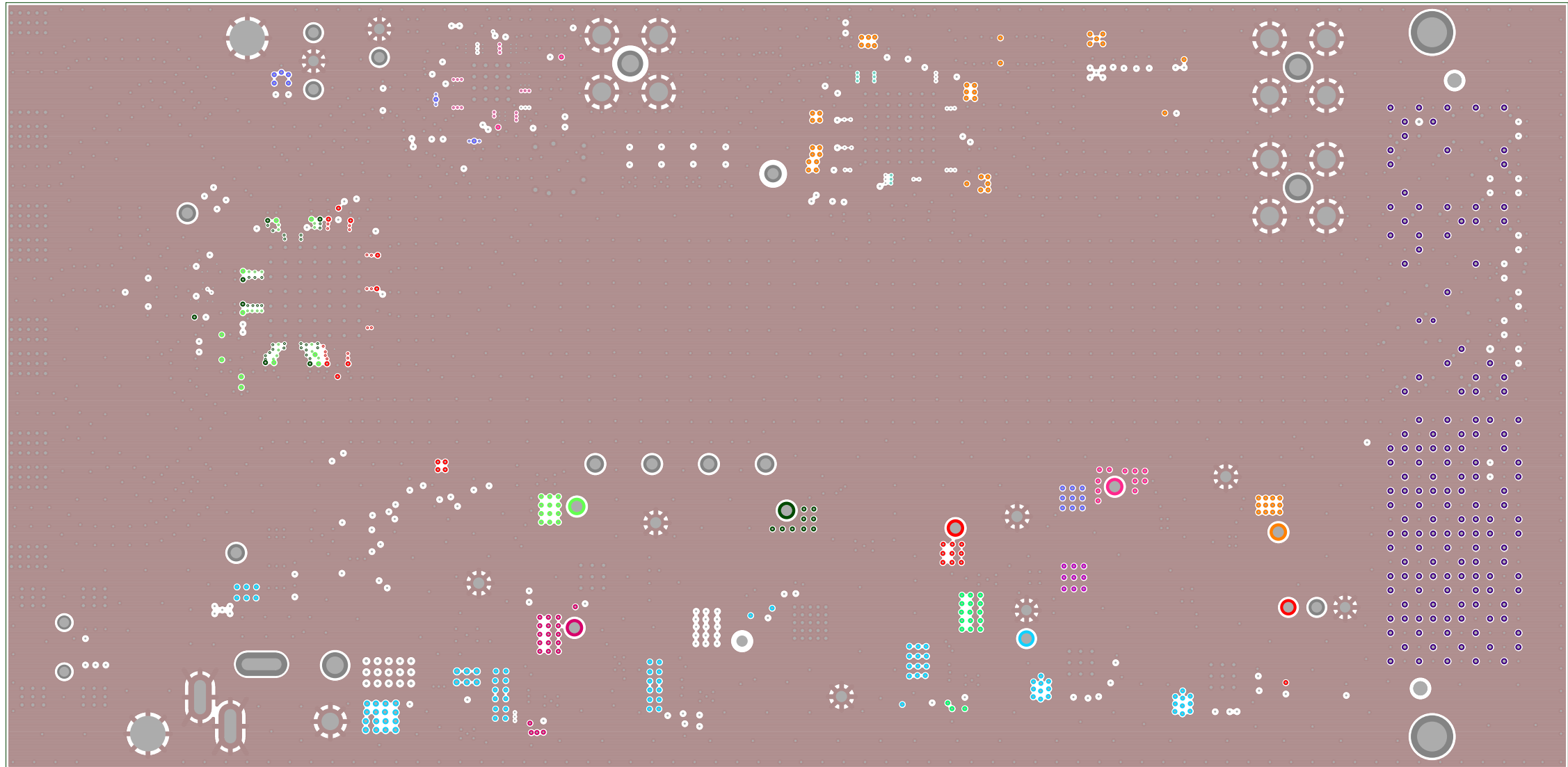
TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 2 - GND



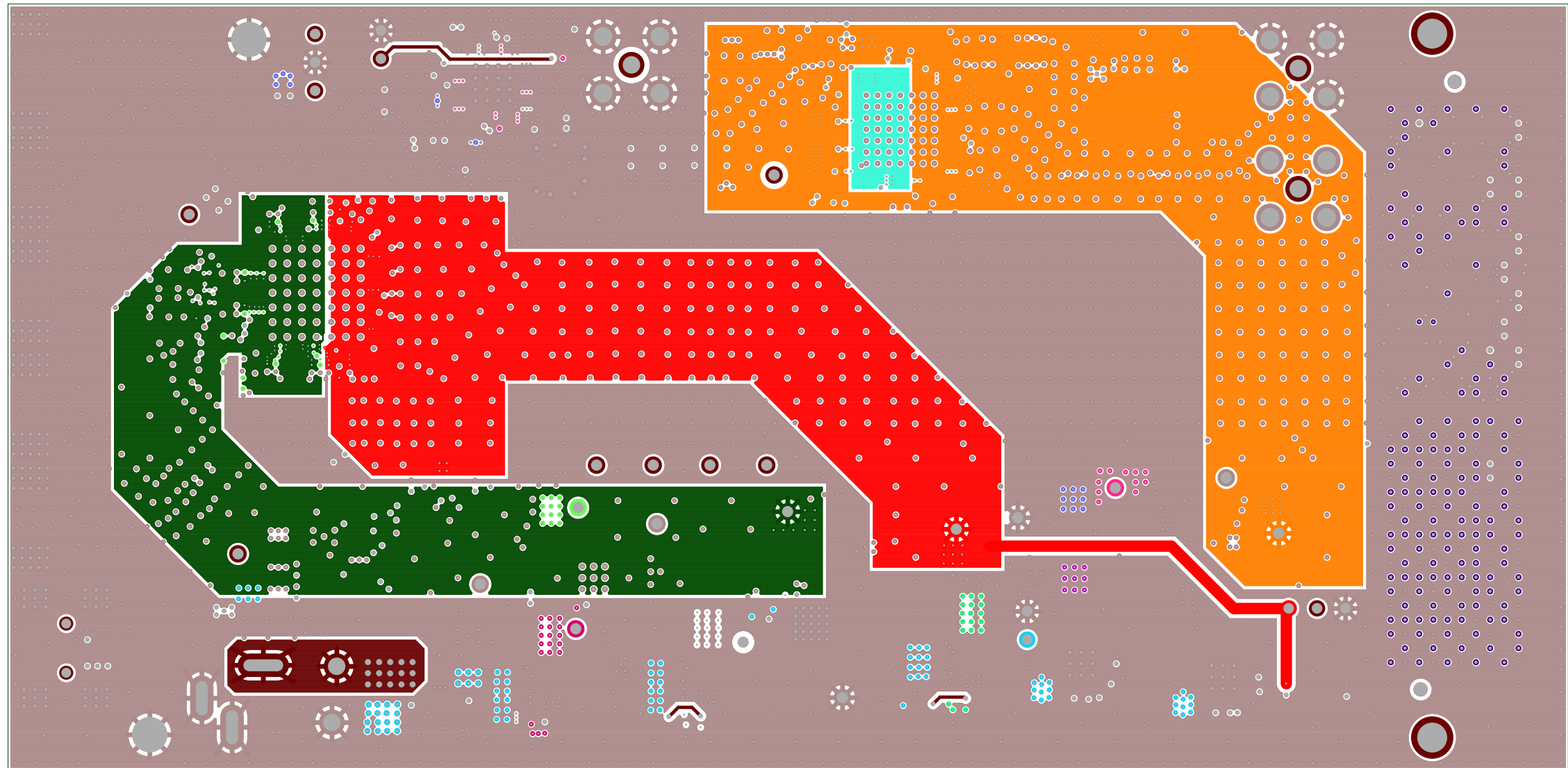
TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 3 - POWER



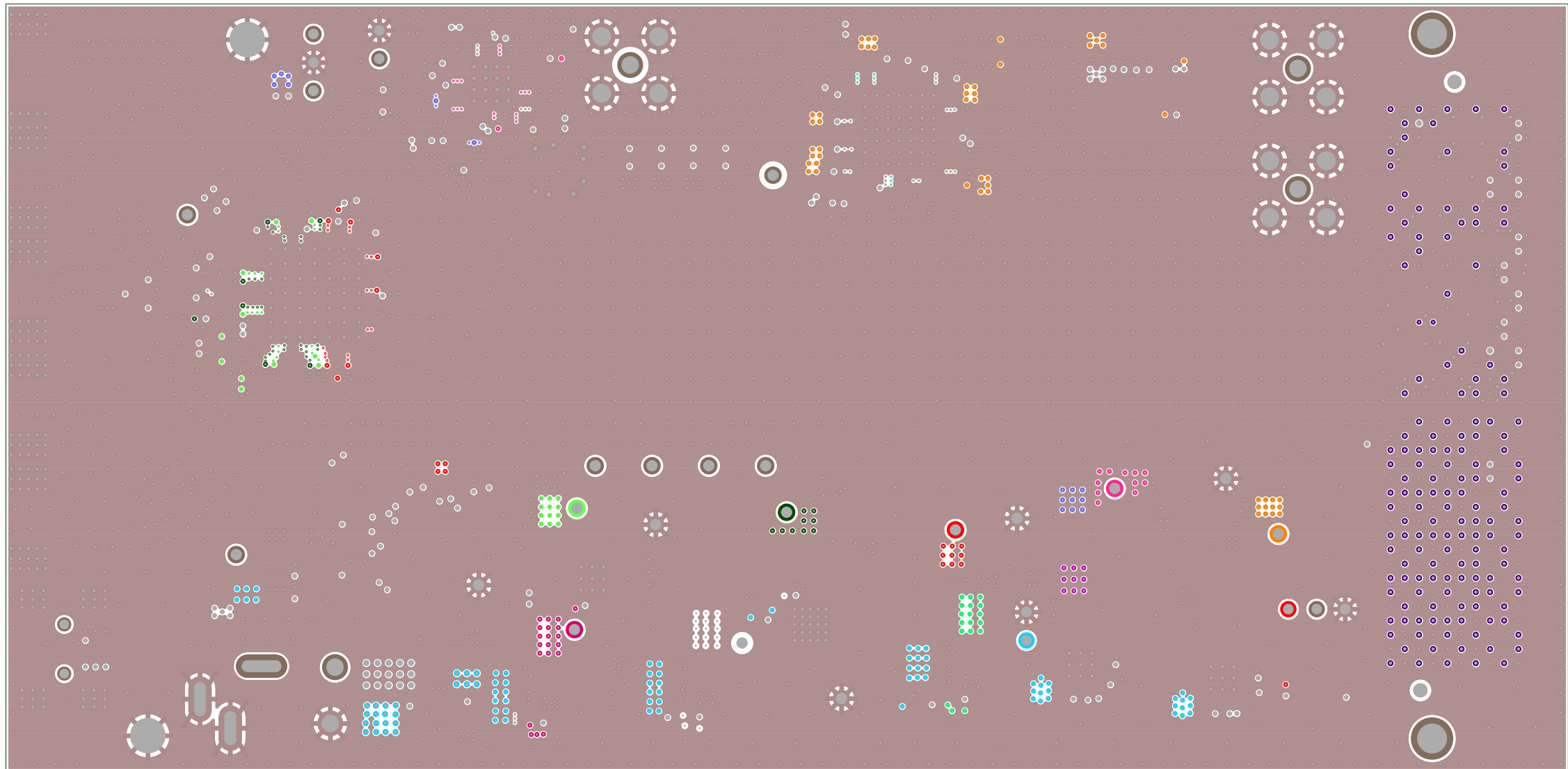
TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 4 - GND



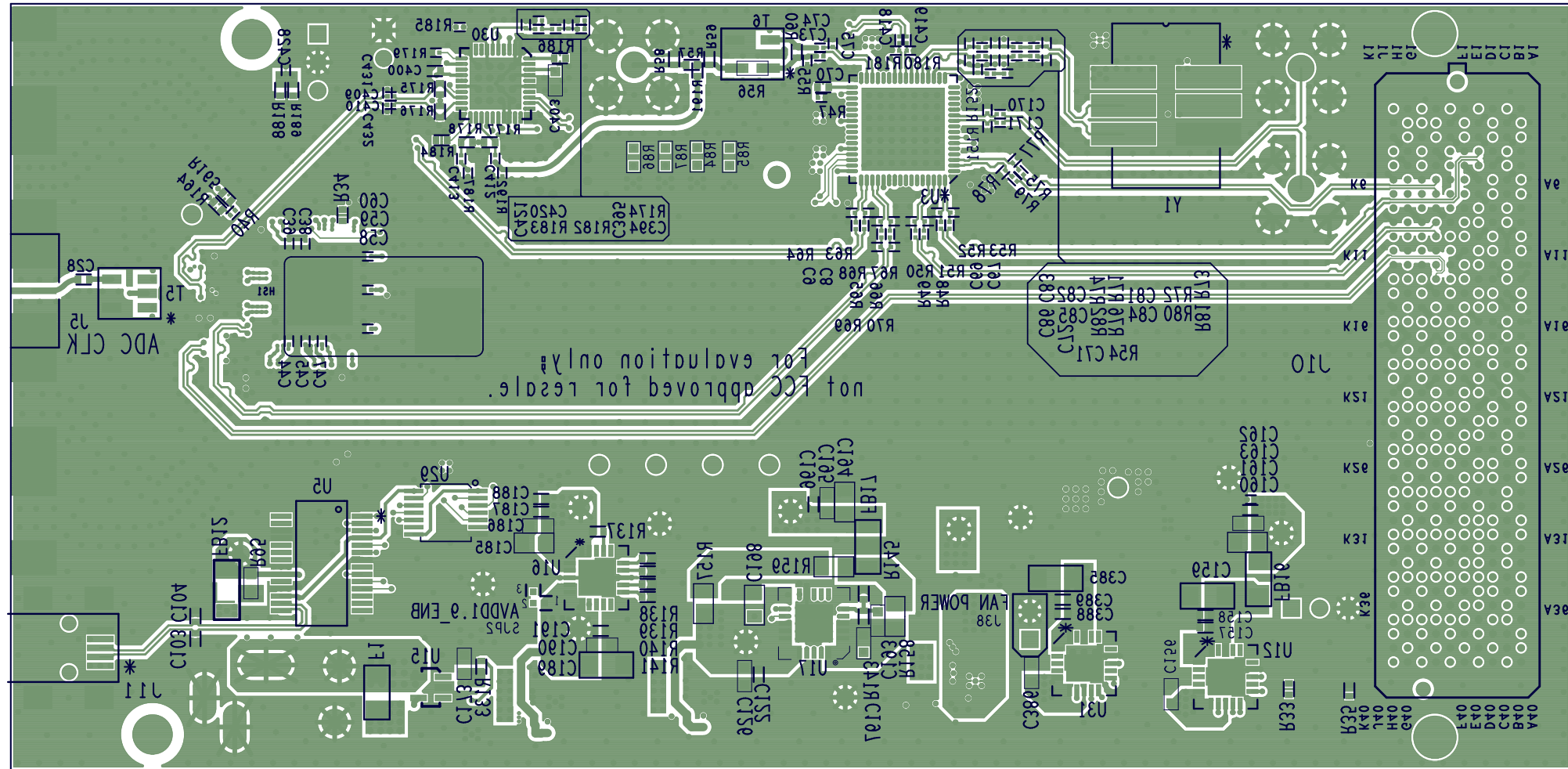
TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 5 - GND



TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 6 - POWER/SIGNAL



TEXAS INSTRUMENTS, INC.
ADC3XRFXXEVM
PCB REV E
LAYER 7 - GROUND



TEXAS INSTRUMENTS, INC.
 ADC3XRFXXEVM
 PCB REV E
 LAYER SCREEN BOTTOM

8

7

6

5

4

3

2

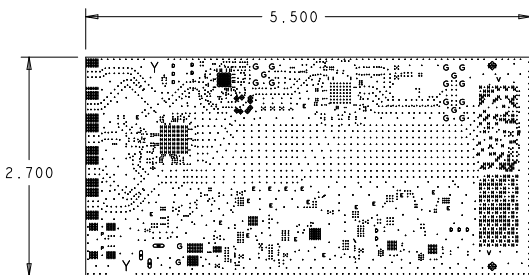
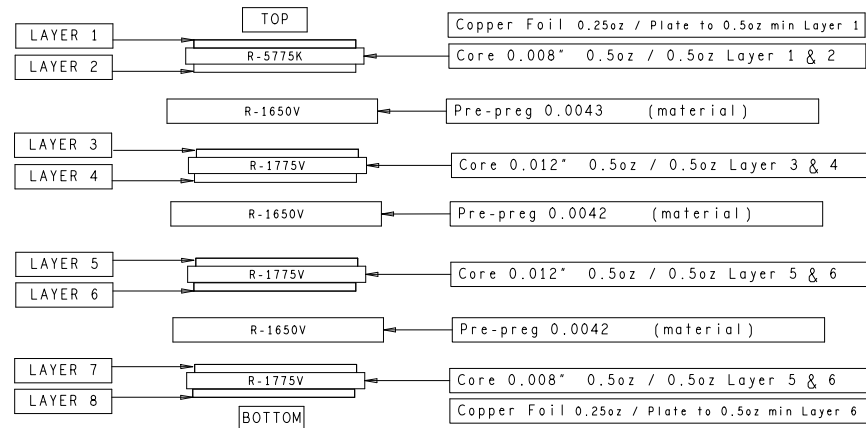
1

REVISIONS				
ZONE	LTR	DESCRIPTION	DATE	APPROVED

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS, IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES, IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, CLASS 2, CURRENT REVISION, IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS, CLASS 2, CURRENT REVISION.
- VIA 8 & 10MIL SIZES APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003 / - .010$. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003$.
- REGISTRATION TOLERANCE: ARTWORK $\pm .002$. ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH. FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0. MATERIAL: MULTI-LAYER (SEE DETAIL "A") SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: $.060 \pm 10\%$
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SMOBC/IMMERSION GOLD: 2 - 8 μ IN OVER 118-236 μ IN NICKEL PLATING.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT) COLOR = RED (0.001 TO 002" THICK OVER METAL).
- SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE. REGISTRATION TOLERANCE TO BE $\pm .005$. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 19MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED $\pm 10\%$.
- 9MIL TRACE WIDTH AND 6MIL SPACING ON TOP SIDE OF BOARD SHALL BE 100 OHMS DIFFERENTIAL $\pm 10\%$. 8MIL TRACE WIDTH AND 6MIL SPACING ON BOTTOM SIDE OF BOARD SHALL BE 100 OHMS DIFFERENTIAL $\pm 10\%$.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 4MIL. MINIMUM COPPER CONDUCTOR SPACING IS: 3.5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY, MAX REFLOW OF 260 DEGREES C (6 PASSES).
- ALL THROUGH VIAS TO BE FILLED WITH NON-CONDUCTIVE MATERIAL. FILLED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE. NO POTHOLES.



TEXAS INSTRUMENTS, INC.
ADC3xRFxxEVM
PCB REV E

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	6.0	PLATED	167
-	8.0	PLATED	2235
-	10.0	PLATED	49
+	12.0	PLATED	508
•	13.0	PLATED	16
+	15.0	PLATED	8
+	38.0	PLATED	10
c	40.0	PLATED	19
o	62.0	PLATED	5
o	67.0	PLATED	12
o	106.0	PLATED	2
Y	125.0	PLATED	2
•	35.0	NON-PLATED	2
v	50.0	NON-PLATED	2
o	118.11x39.37	PLATED	2
o	137.8x39.37	PLATED	1

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES $\pm .XX \pm .01$ $\pm .XXX \pm .005$ \pm	CONTRACT NO.	TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING ADC3xRFxxEVM
MATERIAL	DRAWN L. NGUYEN	08-22-16	
FINISH	ENG R. PRENTICE	08-22-16	REV. E
DO NOT SCALE DRAWING	SEE NOTE 5	SEE NOTE 7, 8, 9	SCALE NONE SHEET 1 OF 1

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